

600V, 15A, Trench FS II IGBT

General Description:

Using NCE's proprietary trench design and advanced FS (field stop) second generation technology, the 600V Trench FS II IGBT offers superior conduction and switching performances, and easy parallel operation;

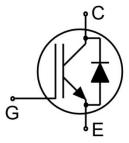
Features

Trench FSII Technology offering

- Very low V_{CE (sat)}
- High speed switching
- Positive temperature coefficient in V_{CE (sat)}
- Very tight parameter distribution
- High ruggedness, temperature stable behavior

Application

- Air Condition
- Inverters
- Motor drives



Schematic diagram

Package Marking and Ordering Information

Device	Device Package	Device Marking
NCE15TD60D	TO-263	NCE15TD60D
NCE15TD60	TO-220	NCE15TD60
NCE15TD60F	TO-220F	NCE15TD60F



TO-263





TO-220

TO-220F

Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	NCE15TD60D NCE15TD60	NCE15TD60F	Units
Vces	Collector-Emitter Voltage	60	V	
V _{GES}	Gate- Emitter Voltage	±30	0	V
	Collector Current	30	30*	Α
lc	Collector Current @T _C = 100 °C	15	15*	Α
I _{Cplus}	Pulsed Collector Current, t _p limited by T _{jmax}	45	45	Α
-	turn off safe operating area, VCE=600V, Tj=150°C	45	45	Α
I _F	Diode Continuous Forward Current @T _C = 100 °C	15	15*	Α
I _{FM}	Diode Maximum Forward Current	45	45	Α
Б	Power Dissipation @ T _C = 25°C	105	35	W
P _D	Power Dissipation @T _C = 100 °C	42	12.8	W
T_J, T_{stg}	Operating Junction and Storage Temperature Range	-55 to +150		$^{\circ}\!\mathbb{C}$
TL	Maximum Temperature for Soldering 260		$^{\circ}$	
t _{sc}	Short circuit withstand time V_{GE} =15.0V, $V_{CC} \le 400V$, Allowed number of short circuits<1000Time between short circuits: $\ge 1.0s$, $T_j \le 150$ °C	10		us



Thermal Characteristic

Symbol	Parameter	NCE15TD60D NCE15TD60	NCE15TD60F	Units
R _{θJC}	Thermal Resistance, Junction to case for IGBT	1.19	3.6	°C/W
R _{θJC}	Thermal Resistance, Junction to case for Diode	1.92	3.9	°C/W
Reja	Thermal Resistance, Junction to Ambient	62	78	°C/W

Electrical Characteristics (Tc=25°Cunless otherwise noted)

Cumahal	Parameter	Took Conditions	Rating			
Symbol		Test Conditions	Min.	Тур.	Max.	Units
OFF Charact	eristics			1		
V _{(BR)CES}	Collector-Emitter Breakdown Voltage	V _{GE} =0V,I _{CE} =1mA	600			V
I _{CES}	Collector-Emitter Leakage Current	V _{GE} =0V,V _{CE} =600V			4	uA
I _{GES(F)}	Gate to Emitter Forward Leakage	V _{GE} =+30V,V _{CE} =0V			100	nA
I _{GES(R)}	Gate to Source Reverse Leakage	V _{GE} =-30V,V _{CE} =0V			100	nA
ON Characte	ristics					
V _{CE(sat)}	Collector-Emitter Saturation Voltage	I _C =15A,V _{GE} =15V		1.8	2.0	V
$V_{\text{GE(th)}}$	Gate Threshold Voltage	I _C =1mA,V _{CE} =V _{GE}	4.0	5.0	6.0	V
Dynamic Cha	aracteristics					
C _{ies}	Input Capacitance)/ 05)/)/ 0\/		649		pF
Coes	Output Capacitance	V _{CE} =25V,V _{GE} =0V, f=1MHz		61		
C _{res}	Reverse Transfer Capacitance	I= I IVIHZ		27		
Q _{Gate}	Gate charge	V _{CC} =480V, I _C =15A V _{GE} =15V		75		nC
I _{C(SC)}	Short circuit collector current Max.1000 short circuits Time between short circuits: ≥1.0s	V_{GE} =15V, V_{CC} \leqslant 400V, t_{SC} \leqslant 10us, Tj \leqslant 150°C		70		А
Switching Cl	haracteristics					
$t_{\text{d}(\text{ON})}$	Turn-on Delay Time			17		
t _r	Rise Time			18		nc
$t_{\text{d(OFF)}}$	Turn-Off Delay Time	V _{CE} =400V,I _C =15A		114		ns
t f	Fall Time	$V_{\text{GE}}\text{=}0/15V,\ R_{g}\text{=}15\Omega$		41		
E _{on}	Turn-On Switching Loss	Inductive Load		0.60		
E _{off}	Turn-Off Switching Loss			0.38		mJ
E _{ts}	Total Switching Loss			0.98		

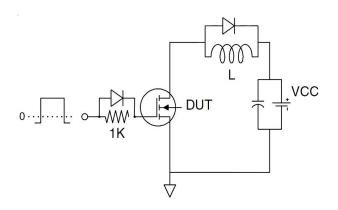
Electrical Characteristics of the Diode (T_C = 25 $^{\circ}$ C unless otherwise specified) :

Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Тур.	Max.	Units
V _{FM}	Diode Forward Voltage	I _F =15A		1.45	1.7	V
T _m	Reverse Recovery Time	\/aa=400\/ =454		122		ns
I _{RRM}	Diode Peak Reverse Recovery Current	Vcc=400V, I _F =15A, di/dt=800A/uS		13		Α
Q _{rr}	Reverse Recovery Charge	ui/ul-600A/uS		1.04		uC
Pulse width t _{tp} ≤380μs,δ≤2%						

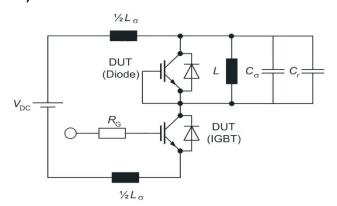


Test Circuit

1) Gate Charge Test Circuit

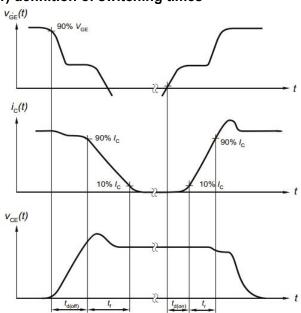


2) Switch Time Test Circuit

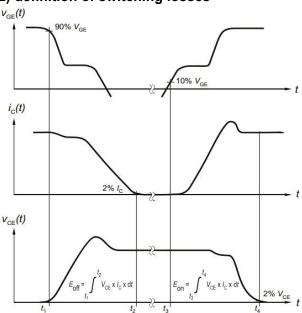


Switching characteristics

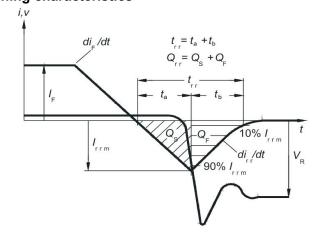
1) definition of switching times



2) definition of switching losses



3) Definition of diode switching characteristics





Typical Electrical and Thermal Characteristics

Figure 1 Output Characteristics

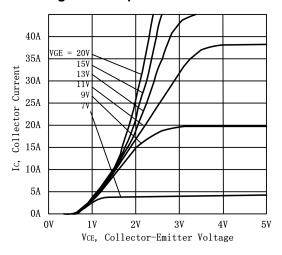


Figure 3 V_{CEsat} vs. Case Temperature

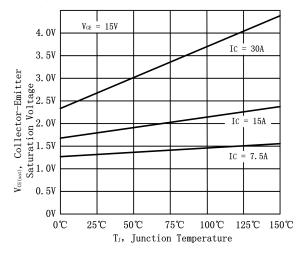


Figure 5 Capacitance Characteristics

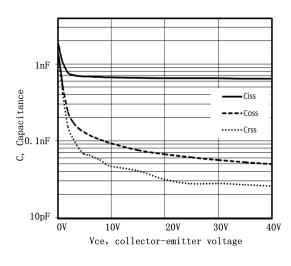


Figure 2. Transfer Characteristics

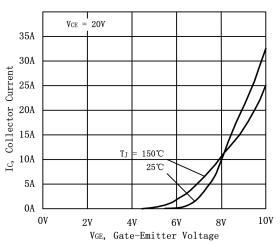


Figure 4 Saturation Voltage vs. VGE

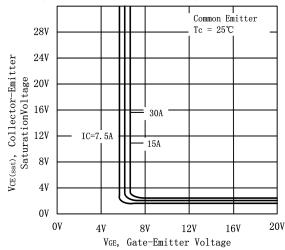
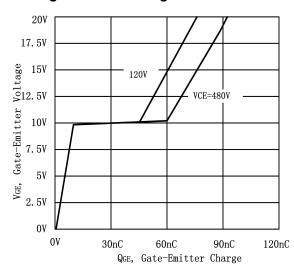


Figure 6 Gate charge waveform



v1.0



Typical Electrical and Thermal Characteristics (continued)

Figure 7. Forward Characteristics

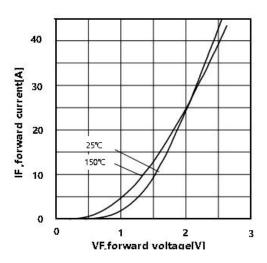


Figure 9. Transient Thermal Impedance of IGBT for TO-220F

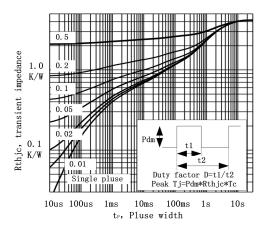


Figure 8 V_F vs. temperature

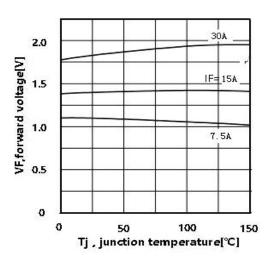
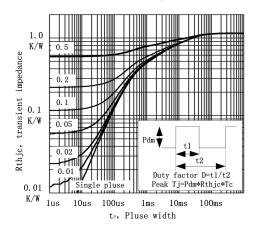
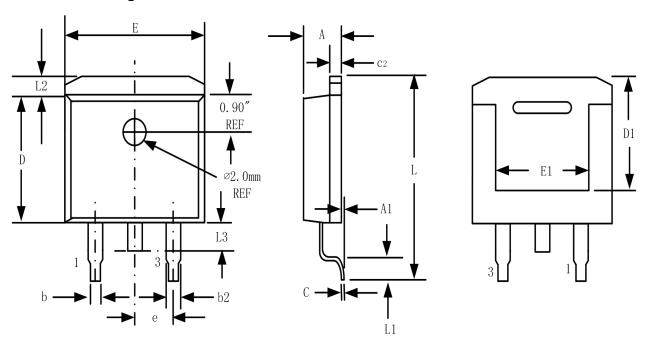


Figure 10. Transient Thermal Impedance of IGBT for TO-220,TO-263





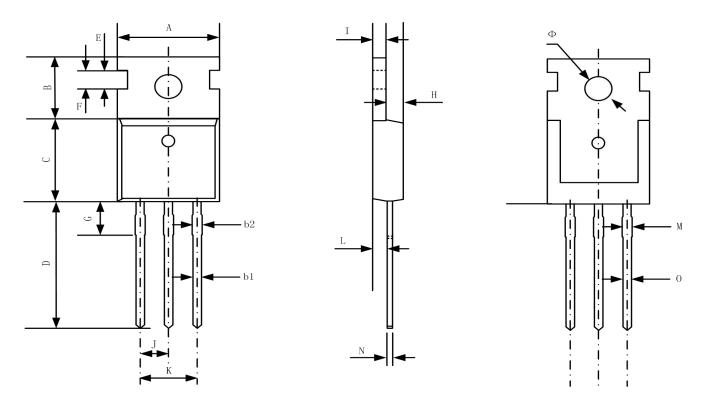
TO-263-3L Package Information



Symbol	Dimensions	Dimensions In Millimeters		s In Inches
Symbol	Min.	Max.	Min.	Max.
А	4.32	4.57	0.170	0.180
A1	-	0.25		0.010
b	0.71	0.94	0.028	0.037
b2	1.15	1.40	0.045	0.055
С	0.46	0.61	0.018	0.024
c2	1.22	1.40	0.048	0.055
D	8.89	9.40	0.350	0.370
D1	8.01	8.23	0.315	0.324
E	10.04	10.28	0.395	0.405
E1	7.88	8.08	0.310	0.318
е	2.54	BSC	0.100 BSC	
L	14.73	15.75	0.580	0.620
L1	2.29	2.79	0.090	0.110
L2	1.15	1.39	0.045	0.055
L3	1.27	1.77	0.050	0.070



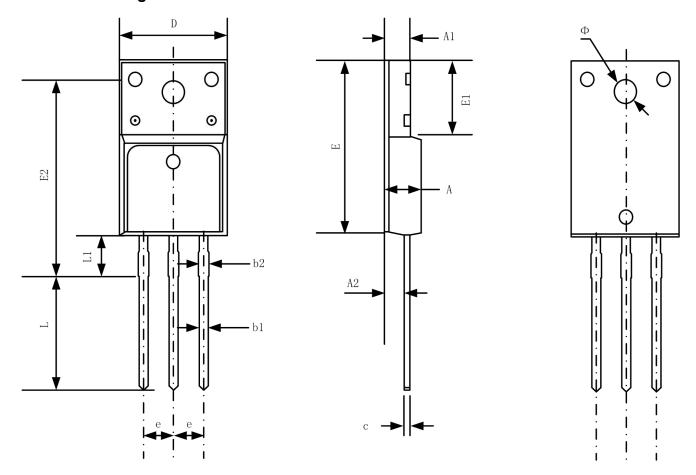
TO-220-3L-C Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	9.70	10.10	0.38	0.40	
В	6.30	6.70	0.25	0.26	
С	9.00	9.47	0.35	0.37	
D	12.80	13.30	0.50	0.52	
E	1.20	1.40	0.05	0.06	
F	1.70 REF		0.067 REF		
G	2.65 REF		0.104 REF		
Н	3.00	3.40	0.12	0.13	
I	1.25	1.40	0.05	0.06	
J	2.40	2.70	0.09	0.11	
K	5.00	5.15	0.20	0.20	
L	2.20	2.60	0.09	0.10	
M	1.25	1.45	0.05	0.06	
N	0.45	0.60	0.02	0.02	
0	0.70	0.90	0.03	0.04	
Ф	3.6	REF	0.142 REF		



TO-220F Package Information



Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A	4.500	4.900	0.177	0.193	
A1	2.340	2.740	0.092	0.108	
A2	2.560	2.960	0.101	0.117	
b1	0.700	0.900	0.028	0.035	
b2	1.180	1.580	0.046	0.062	
С	0.400	0.600	0.016	0.024	
D	9.960	10.360	0.392	0.408	
E	15.670	15.970	0.617	0.629	
E1	6.500	6.900	0.256	0.272	
E2	15.500	16.100	0.610	0.634	
е	2.540	540 TYP 0.100 T		TYP	
Ф	3.080	3.280	0.121	0.129	
L	12.640	13.240	0.498	0.521	
L1	3.030	3.430	0.119	0.135	



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